



ionDesign, Inc.

# CUSTOMER INPUT CHECKLIST FOR PCB DESIGN

Customer: \_\_\_\_\_ Contact: \_\_\_\_\_ Phone: \_\_\_\_\_  
Quote due by: \_\_\_\_\_ Email address \_\_\_\_\_

- \_\_\_\_\_ Electronic schematic (*REQUIRED FOR QUOTE*)
- \_\_\_\_\_ Bill of materials (*REQUIRED FOR QUOTE*)
- \_\_\_\_\_ Electronic BOM with Ref. Des.
- \_\_\_\_\_ Mechanical drawing with Critical placement / keepouts (*REQUIRED FOR QUOTE*)
- \_\_\_\_\_ All datasheets at start of job.
- \_\_\_\_\_ Statement of work (SOW) (*REQUIRED FOR QUOTE*)
- \_\_\_\_\_ Routing rules / Placement rules

PCB NAME: \_\_\_\_\_ P/N: \_\_\_\_\_  
 FAB DWG. P/N: \_\_\_\_\_ ASSY DWG. P/N: \_\_\_\_\_  
 BARE BOARD P/N: \_\_\_\_\_ BOARD ASSY P/N: \_\_\_\_\_  
 PART NUMBER REV LEVEL ETCH REQUIREMENTS: \_\_\_\_\_  
 COMPANY NAME & LOGO REQUIREMENTS: \_\_\_\_\_

TECHNOLOGY: (*ENTER PERCENT*) \_\_\_\_\_ % DIGITAL \_\_\_\_\_ % ANALOG \_\_\_\_\_ % RF

PERCENTAGE OF DESIGN CRITICAL: (*ANALOG/RF IS ALWAYS CONSIDERED CRITICAL*) \_\_\_\_\_ %

LIST ADVANCED TECHNOLOGY: (*i.e. RAMBUS*) \_\_\_\_\_

LIST HDI PACKAGES: (*i.e. BGA PITCH < 1.27mm*) \_\_\_\_\_

**CONTROLLED IMPEDANCE:**

MICROSTRIP/BURIED MICROSTRIP: \_\_\_\_\_ NO \_\_\_\_\_ YES: \_\_\_\_\_ OHMS +/- \_\_\_\_\_ %  
 STRIPLINE/DUAL STRIPLINE: \_\_\_\_\_ NO \_\_\_\_\_ YES: \_\_\_\_\_ OHMS +/- \_\_\_\_\_ %  
 EDGE/BROADSIDE DIFFERENTIAL : \_\_\_\_\_ NO \_\_\_\_\_ YES: \_\_\_\_\_ OHMS +/- \_\_\_\_\_ %

DIFFERENTIAL PAIRS: \_\_\_\_\_ NO \_\_\_\_\_ YES: \_\_\_\_\_ APPROX. NUMBER OF PAIRS

LAYER COUNT: \_\_\_\_\_ MATERIAL TYPE: \_\_\_\_\_ THICKNESS: \_\_\_\_\_ COPPER WEIGHT: \_\_\_\_\_

**STANDARD DELIVERABLES: COMPLETE DATABASE, FAB DWG, ASSY DWG, DRILL AND GERBER DATA  
IPC TEST DATA, PICK AND PLACE DATA, SOLDER PASTE DATA.**

ADDITIONAL DELIVERABLES REQUIRED? \_\_\_\_\_

ADDITIONAL INFORMATION: \_\_\_\_\_